

CERAMIC BALUN

RF Transformer

TCW2-2700-1+

50Ω 500 to 2700 MHz 1:2 Ratio

THE BIG DEAL

- Wideband. 500-2700 MHz
- Miniature size 0603 (1.6x0.8mm)
- LTCC construction
- Low cost
- Aqueous washable



Generic photo used for illustration purposes only

CASE STYLE: JC0603C

+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our website for methodologies and qualifications

APPLICATIONS

- L-Band
- A/D conversion
- GPS
- Cellular

PRODUCT OVERVIEW

Mini-Circuits' TCW2-2700-1+ is a tiny ceramic RF balun transformer with an impedance ratio of 1:2, covering a variety of wireless communications applications from 500 to 2700 MHz. This model provides, low amplitude unbalance, and RF input power handling up to 0.5W. It provides DC isolation from input to output allowing it to be used for DC biasing of external circuits at the output. Fabricated using LTCC technology, the unit comes housed in a tiny, rugged ceramic package (0.06 x 0.03 x 0.02") suitable for harsh operating environments.

KEY FEATURES

Feature	Advantages
Low unbalance, 0.6 dB	Low unbalance can improve a system's electromagnetic compatibility by rejecting unwanted common-mode noise.
Wideband Performance	Supports a wide range of wireless applications.
Tiny size, 0603	Accommodates tight space requirements for dense PCB layouts.
LTCC construction	LTCC process enables tiny size and low cost, suitable for high-volume production. Rugged ceramic package provides excellent reliability in harsh operating environments.

REV. OR
NPO-002681
TCW2-2700-1+
MY/CP/AM
221005





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ELECTRICAL SPECIFICATIONS AT 25°C

Parameter	Frequency (GHz)	Min.	Typ.	Max.	Units
Impedance Ratio (Secondary/ Primary)			2		
Frequency Range		500		2700	MHz
Insertion Loss ¹	500-2700	—	1.3	1.7	dB
Amplitude Unbalance	500-2700	—	0.6	1	dB
Phase Unbalance ²	500-2150	—	—	13	Degree
	2150-2700	—	19	—	
Return Loss	500-2700	9.5	12.5	—	dB

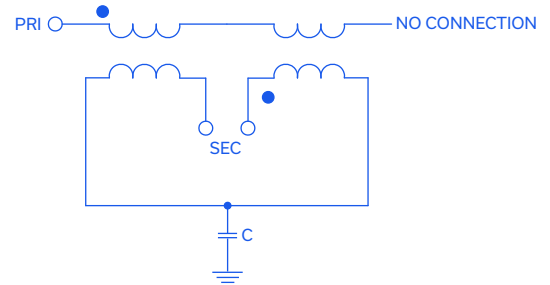
- 1. Reference Demo Board TB-TCW2-2700+
- 2. Relative to 180°

MAXIMUM RATINGS

Parameter	Ratings
Operating Temperature	-55°C to 125°C
Storage Temperature	-55°C to 125°C
RF Power Input	0.5W max.

Permanent damage may occur if any of these limits are exceeded.

CONFIGURATION R





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TCW2-2700-1+



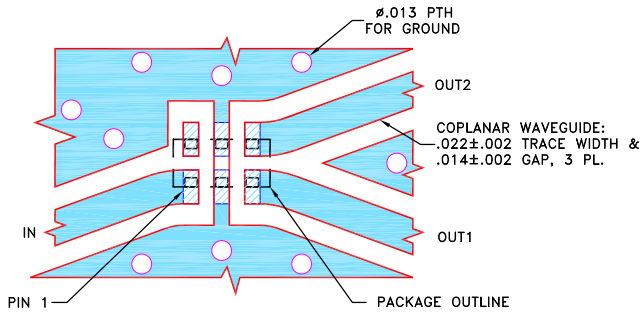
50Ω 500 to 2700 MHz 1:2 Ratio

PAD CONNECTIONS

PRIMARY DOT	1
GND or DC feed + RF	2
SECONDARY DOT	3
SECONDARY	4
NO CONNECTION	6
GND	5

PRODUCT MARKING: N/A

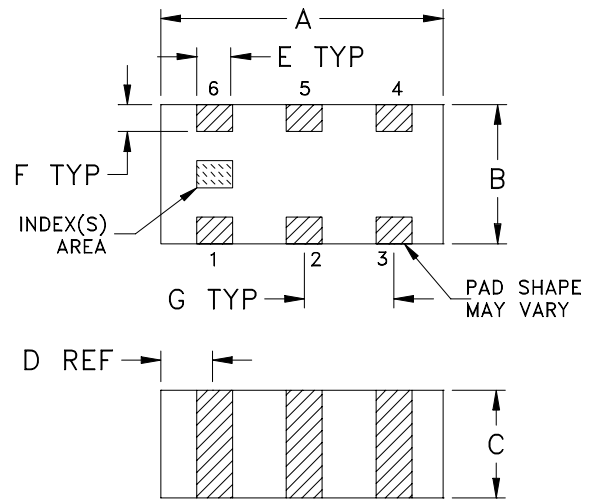
DEMO BOARD MCL P/N: TB-TCW2-2700+ SUGGESTED PCB LAYOUT (PL-513)



- TRACE WIDTH AND GAP PARAMETERS ARE SHOWN FOR ROGERS R04350B WITH DIELECTRIC THICKNESS $.010 \pm .001$ ". COPPER: 1/2 OZ. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.
- BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

- DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER).
- DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

OUTLINE DRAWING



OUTLINE DIMENSIONS (Inches/mm)

A	B	C	D	E	F	G	wt
.063	.031	.024	.012	.008	.006	.020	grams
1.60	0.79	0.61	0.30	0.20	0.15	0.51	0.005

TAPE & REEL INFORMATION: F114





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RF Transformer

TCW2-2700-1+

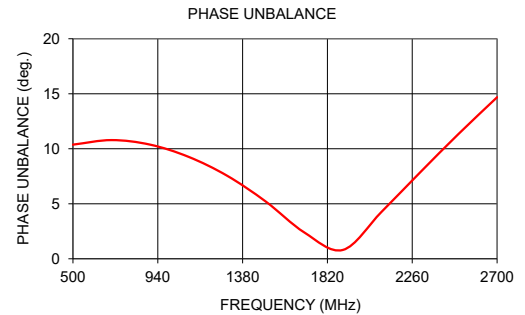
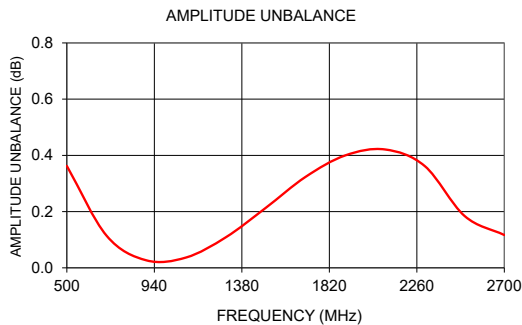
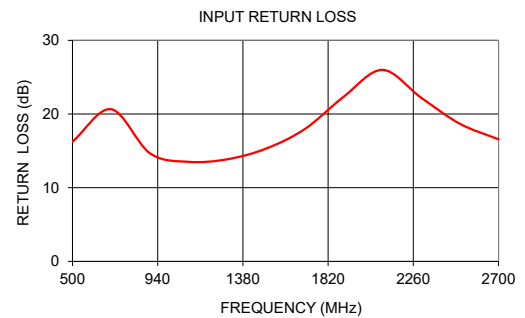
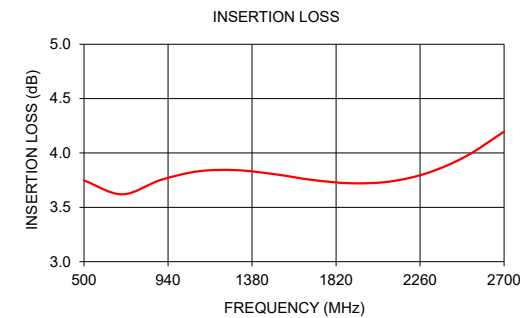


50Ω 500 to 2700 MHz 1:2 Ratio

TYPICAL PERFORMANCE DATA³

Frequency (MHz)	Insertion Loss (dB)	Input Return Loss (dB)	Amplitude Unbalance (dB)	Phase Unbalance (deg)
500	3.75	16.25	0.36	10.38
700	3.62	20.65	0.11	10.79
900	3.75	14.67	0.03	10.38
1100	3.83	13.51	0.04	9.26
1300	3.84	13.86	0.11	7.55
1500	3.80	15.31	0.21	5.20
1700	3.75	17.97	0.32	2.39
1900	3.72	22.34	0.40	0.80
2100	3.74	25.99	0.42	4.25
2300	3.82	22.22	0.36	7.84
2500	3.97	18.68	0.18	11.35
2700	4.20	16.57	0.12	14.68

3. Measured with Agilent E5071B network analyzer using impedance conversion and port extension.



- NOTES**
- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
 - B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.
 - C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the standard. Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/terms/viewterm.html



Tape & Reel Packaging TR-F114

DEVICE ORIENTATION IN T&R



ILLUSTRATION 1

Applicable Case Styles	
GE0805C	JC0603C
GE0805C-1	JC0603C-4
GE0805C-1AP	JC0603C-6
GE0805C-7	
GE0805C-9	
GE0805C-10	
GE0805C-11	
GE0805C-12	

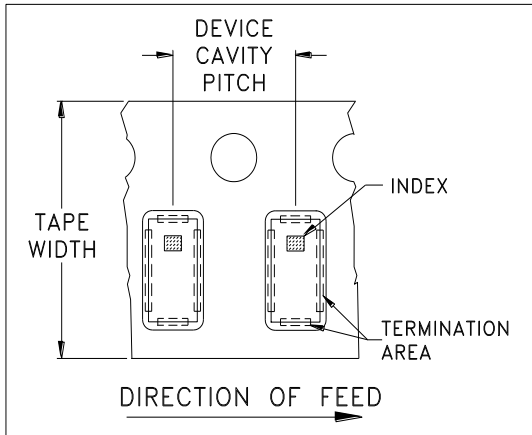


ILLUSTRATION 2

Applicable Case Styles	
GE0805C-2	JC0603C-1
GE0805C-3	JC0603C-2
GE0805C-4	JC0603C-3
GE0805C-5	JC0603C-5
GE0805C-6	JC0603C-7
GE0805C-8	
GE0805C-15	

Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel	
8	4	7	Small quantity standards (see note)	20
				50
				100
				200
				500
				1000
			Standard	4000

Note: Please Consult individual model data sheet to determine device per reel availability.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf



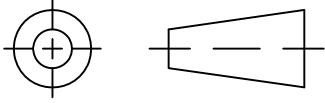
INTERNET <http://www.minicircuits.com>

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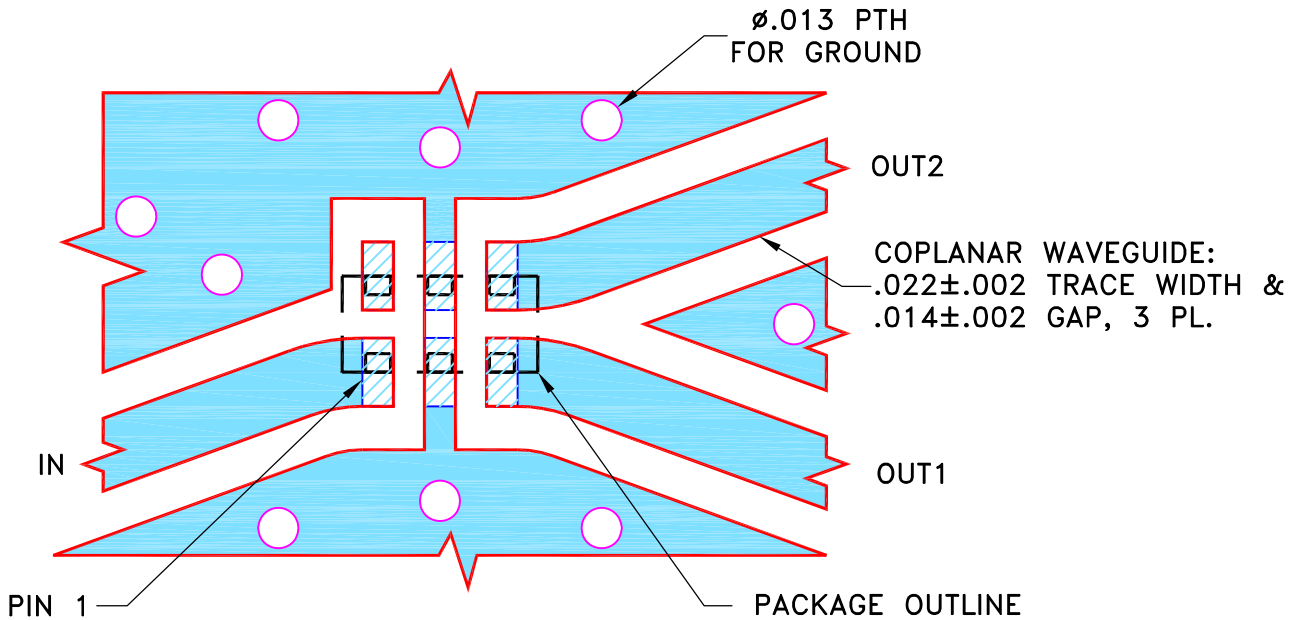
THIRD ANGLE PROJECTION




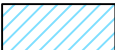
REVISIONS

REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	M162337	NEW RELEASE	06/15/17	ITG	AVB

**SUGGESTED MOUNTING CONFIGURATION
FOR JC0603C CASE STYLE, "06TR01" PIN CODE**



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2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

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 DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK.

UNLESS OTHERWISE SPECIFIED	INITIALS		DATE
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS ± 3 PL DECIMALS ± .005 ANGLES ± FRACTIONS ±	DRAWN	ITG	06/14/17
	CHECKED	GF	06/15/17
	APPROVED	AVB	06/15/17

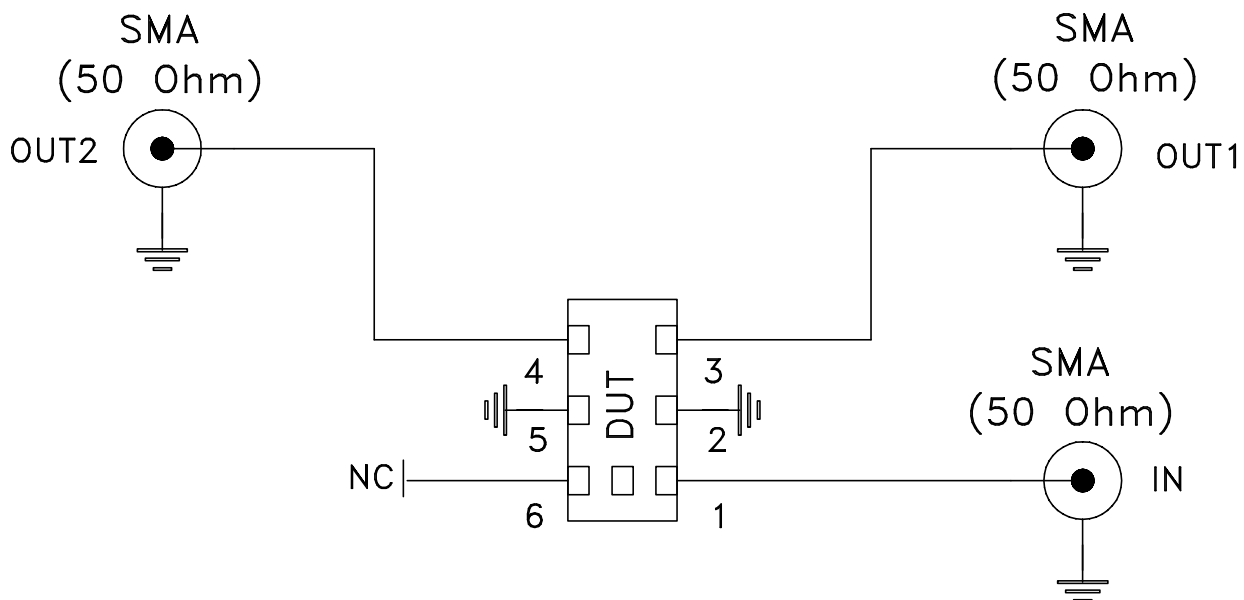
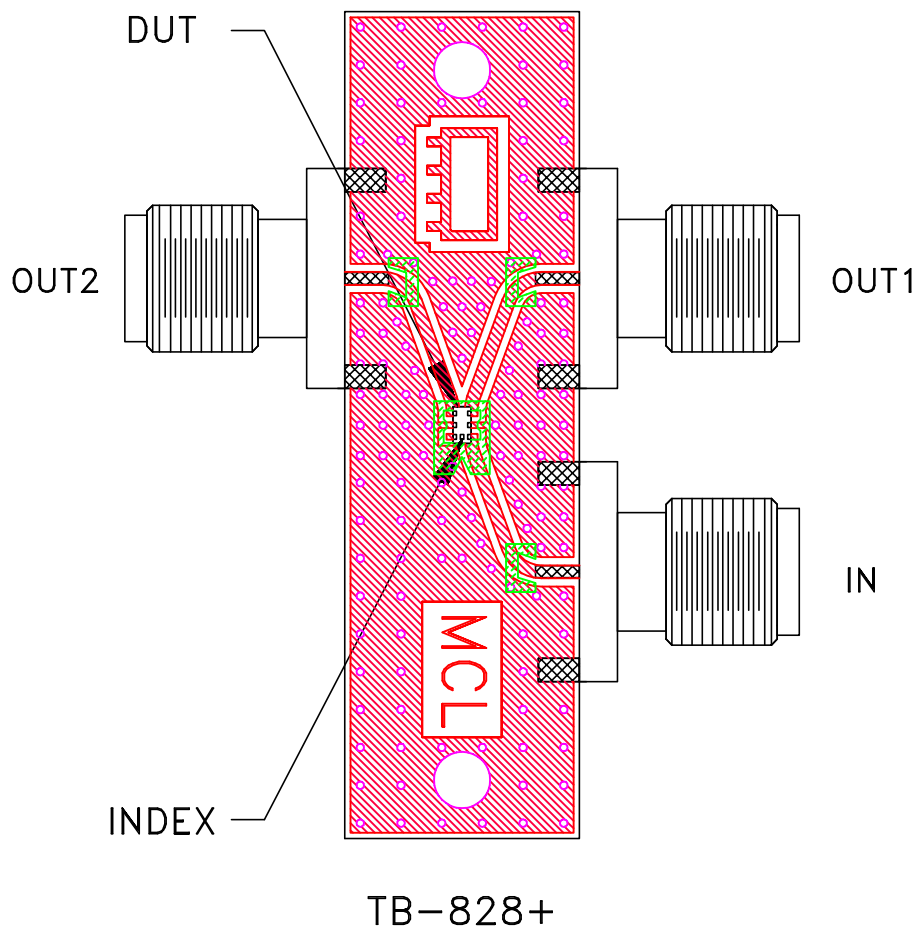
 **Mini-Circuits®** 13 Neptune Avenue
Brooklyn NY 11235

PL, 06TR01, JC0603C, TB-828+

SIZE A	CODE IDENT 15542	DRAWING NO: 98-PL-513	REV: OR
FILE: 98PL513	SCALE: 16:1	SHEET: 1 OF 1	


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Evaluation Board and Circuit



Notes:

1. 50 Ohm SMA Female connectors.
2. PCB Material: R04350 or equivalent,
Dielectric Constant=3.5, Thickness=.010 inch.

 **Mini-Circuits®**

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 100°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, Para 4.2.5, Test S, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A